



# UM6116-5

## 2K × 8 High Speed CMOS SRAM

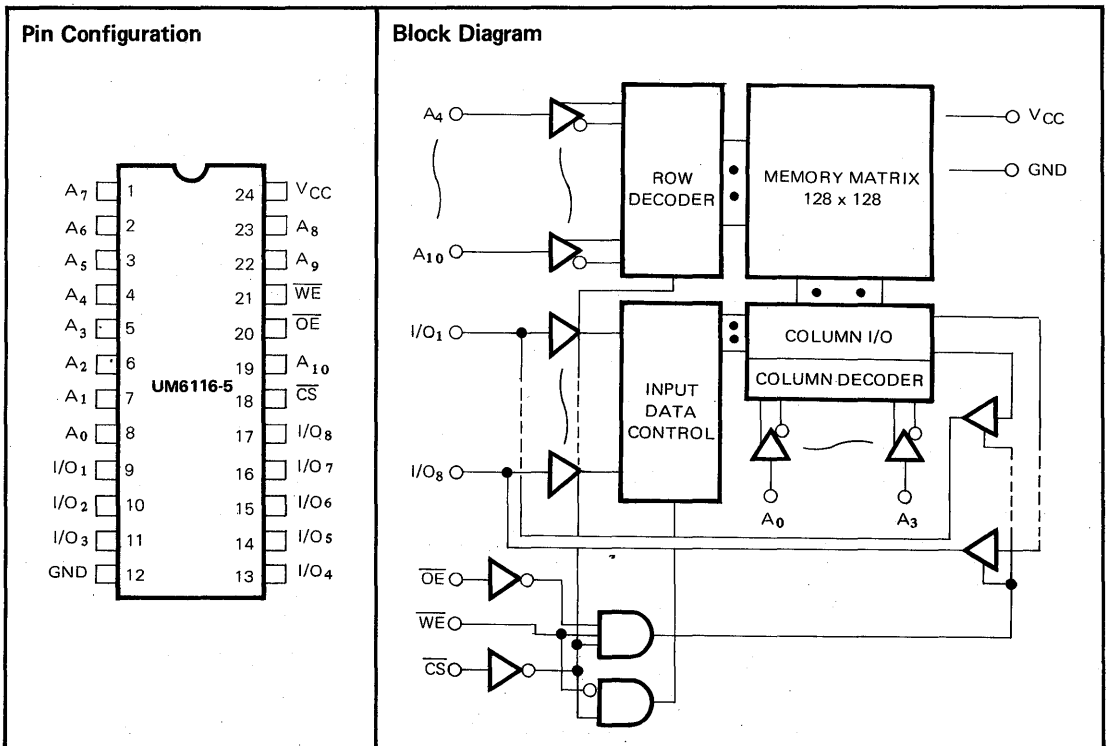
### Features

- Single 5V supply and high density 24 pin package
- High speed: Fast access time 55ns (max.)
- Low power standby and Low power operation Standby: 5 μW (typ.) Operation: 250mW (typ.)
- Completely static RAM: No clock or timing strobe required
- Directly TTL compatible: All input and output
- Pin compatible with standard 16K EPROM/Mask ROM
- Equal access and cycle time

### General Description

The UM6116 is a 16,384-bit static random access memory organized as 2048 words by 8 bits and operates from a single 5 volt supply. It is built with UMC's high performance CMOS process. Six-transistor full CMOS memory cell

provides low standby current and high-reliability. Inputs and three-state outputs are TTL compatible and allow for direct interfacing with common system bus structures. The UM6116 is moulded in a standard 24-pin 600mil-DIP.



**Absolute Maximum Ratings**

Voltage on Any Pin Relative to GND,  $V_T$  . . . -0.3V to +7.0V  
 Operating Temperature,  $T_{opr}$  . . . . . 0°C to +70°C  
 Storage Temperature (Plastic),  $T_{stg}$  . . . . -55°C to +125°C  
 Temperature Under Bias,  $T_{bias}$  . . . . . -10°C to +85°C  
 Power Dissipation,  $P_T$  . . . . . 1.0W

**\*Comments**

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of this device at these or any other conditions above those indicated in the operational sections of this specification is not implied and exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**Truth Table**

$\overline{CS}$	$\overline{OE}$	$\overline{WE}$	Mode	$V_{CC}$ Current	I/O Pin
H	x	x	Standby	$I_{SB}, I_{SBT}$	High Z
L	L	H	Read	$I_{CC}$	Dout
L	H	H	Read	$I_{CC}$	High Z
L	x	L	Write	$I_{CC}$	Din

SRAM

**D.C. and Operating Characteristics**

( $V_{CC} = 5V \pm 5\%$ ,  $GND = 0V$ ,  $T_A = 0$  to +70°C)

Item	Symbol	Test Conditions	6116-5			Units
			Min.	Typ.*	Max.	
Input Leakage Current	$I_{LI}$	$V_{CC} = 5.5V, V_{IN} = GND$ to $V_{CC}$	—	—	10	$\mu A$
Output Leakage Current	$I_{LO}$	$\overline{CS} = V_{IH}$ or $\overline{OE} = V_{IH}$ , $V_{I/O} = GND$ to $V_{CC}$	—	—	10	$\mu A$
Operating Power Supply Current	$I_{CC}$	$\overline{CS} = V_{IL}, I_{I/O} = 0mA$	—	50	100	mA
	$I_{CC1}$	$V_{IH} = 3.5V, V_{IL} = 0.6V$ , $I_{I/O} = 0mA$	—	45	—	mA
Dynamic Operating Current	$I_{CC2}$	Min. cycle, duty=100%	—	—	100	mA
Standby Power Supply Current	$I_{SB}$	$\overline{CS} = V_{IH}$	—	5	10	mA
	$I_{SB1}$	$\overline{CS} \geq V_{CC} - 0.2V, V_{IN} \geq V_{CC} - 0.2V$ or $V_{IN} \leq 0.2V$	—	1	50	$\mu A$
Output Voltage	$V_{OL}$	$I_{OL} = 4mA$	—	—	0.4	V
	$V_{OH}$	$I_{OH} = -1.0mA$	2.4	—	—	V
Input Voltage	$V_{IH}$		2.2	3.5	5.8	V
	$V_{IL}$		-0.3	—	+0.8	V

\* $V_{CC} = 5V, T_A = 25^\circ C$

**A.C. Characteristics** ( $V_{CC} = 5V \pm 5\%$ ,  $T_A = 0$  to  $+70^\circ\text{C}$ )

**A.C. Test Conditions**

Input Pulse Levels: 0V to 3.0V

Input Rise and Fall Times: 5ns

Input and Output Timing Reference Levels: 1.5V

Output Load: 1TTL Gate and  $C_L = 30\text{pF}$  (including scope and jig)

**READ CYCLE**

Item	Symbol	6116-5		Unit
		Min.	Max.	
Read Cycle Time	$t_{RC}$	55	—	ns
Address Access Time	$t_{AA}$	—	55	ns
Chip Select Access Time	$t_{ACS}$	—	55	ns
Chip Selection to Output in Low Z	$t_{CLZ}$	5	—	ns
Output Enable to Output Valid	$t_{OE}$	—	35	ns
Output Enable to Output in Low Z	$t_{OLZ}$	5	—	ns
Chip Deselection to Output in High Z	$t_{CHZ}$	0	30	ns
Chip Disable to Output in High Z	$t_{OHZ}$	0	25	ns
Output Hold from Address Change	$t_{OH}$	5	—	ns

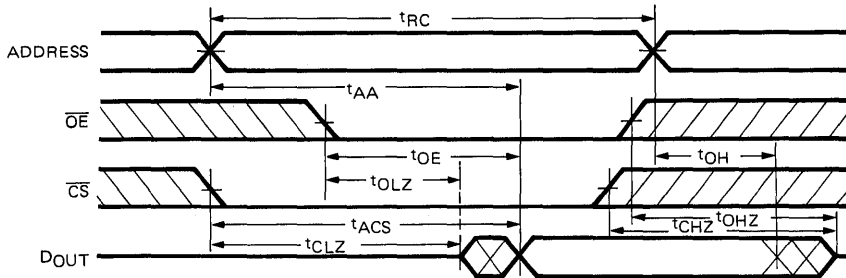
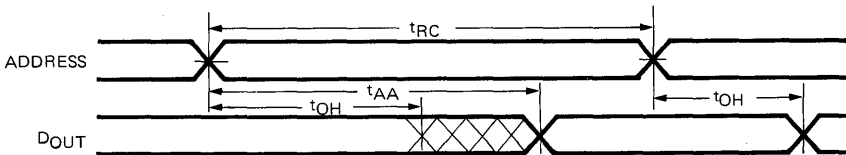
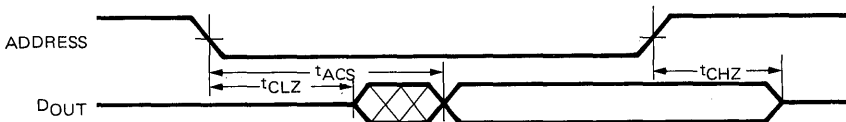
**WRITE CYCLE**

Item	Symbol	6116-5		Unit
		Min.	Max.	
Write Cycle Time	$t_{WC}$	55	—	ns
Chip Selection to End of Write	$t_{CW}$	40	—	ns
Address Valid to End of Write	$t_{AW}$	50	—	ns
Address Set Up Time	$t_{AS}$	5	—	ns
Write Pulse Width	$t_{WP}$	40	—	ns
Write Recovery Time	$t_{WR}$	5	—	ns
Output Disable to Output in High Z	$t_{OHZ}$	0	25	ns
Write to Output in High Z	$t_{WHZ}$	0	25	ns
Data to Write Time Overlap	$t_{DW}$	25	—	ns
Data Hold from Write Time	$t_{DH}$	5	—	ns
Output Active from End of Write	$t_{OW}$	0	—	ns

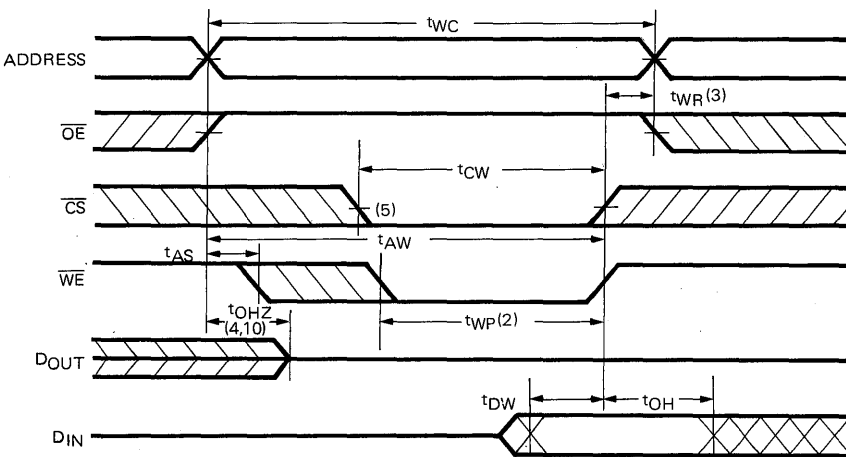
**Capacitance\*** ( $f = 1\text{MHz}$ ,  $T_A = 25^\circ\text{C}$ )

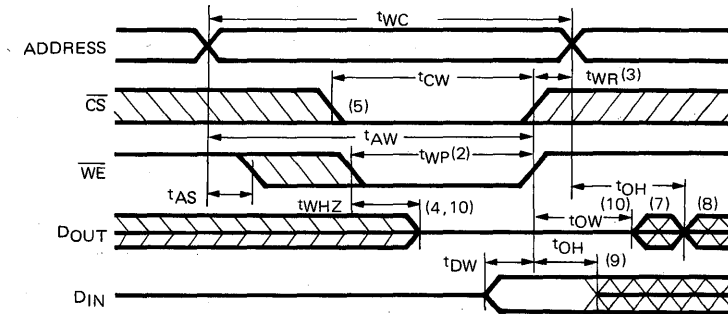
Item	Symbol	Test Conditions	Max.	Unit
Input Capacitance	$C_{in}$	$V_{in} = 0V$	8	pF
Input/Output Capacitance	$C_{I/O}$	$V_{I/O} = 0V$	10	pF

\*This parameter is sampled and not 100% tested.

**Timing Waveform**
**READ CYCLE (1)<sup>(1)(5)</sup>**

**READ CYCLE (2)<sup>(1)(2)(4)</sup>**

**READ CYCLE (3)<sup>(1)(3)(4)(5)</sup>**

**Notes:**

1.  $\overline{WE}$  is High for Read Cycle.
2. Device is continuously selected,  $\overline{CS} = V_{IL}$ .
3. Address Valid prior to or coincident with  $\overline{CS}$  transition Low.
4.  $\overline{OE} = V_{IL}$ .
5. Transition is measured  $\pm 500mV$  from steady state. This parameter is sampled and not 100% tested.

**WRITE CYCLE (1)**

**SRAM**

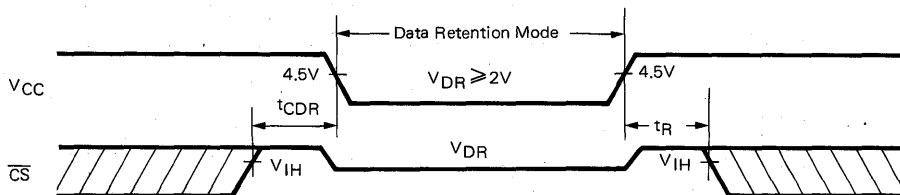
**WRITE CYCLE (2)(1)(6)**

**Notes:**

1.  $\overline{WE}$  must be high during all address transitions.
2. A write occurs during the overlap ( $t_{WP}$ ) of a low  $\overline{CS}$  and a low  $\overline{WE}$ .
3.  $t_{WR}$  is measured from the earlier of  $\overline{CS}$  or  $\overline{WE}$  going high to the end of write cycle.
4. During this period, I/O pins are in the output state so that the input signals of opposite phase to the outputs must not be applied.
5. If the  $\overline{CS}$  low transition occurs simultaneously with the  $\overline{WE}$  low transitions or after the  $\overline{WE}$  transition, outputs remain in a high impedance state.
6.  $\overline{OE}$  is continuously low ( $\overline{OE} = V_{IL}$ ).
7.  $D_{OUT}$  is the same phase of write data of this write cycle.
8.  $D_{OUT}$  is the read data of next address.
9. If  $\overline{CS}$  is low during this period, I/O pins are in the output state. Then the data input signals of opposite phase to the outputs must not be applied to them.
10. Transition is measured  $\pm 500\text{mV}$  from steady state. This parameter is sampled and not 100% tested.

**Data Retention Characteristics** over the operating temperature range

Symbol	Parameter	Test Conditions	Min.	Typ.(1)	Max.	Units
$V_{DR}$	$V_{CC}$ for Retention Data	$\overline{CS} = V_{CC}$	2.0	—	—	V
$I_{CCDR}$	Data Retention Current	$V_{IN} = 0\text{V}$ or $V_{CC}$	—	2	20	$\mu\text{A}$
$t_{CDR}$	Chip Deselect to Data Retention Time	$V_{CC} = 2.0\text{V}$ , $\overline{CS} = V_{CC}$	0	—	—	ns
$t_R$	Operation Recovery Time	$V_{IN} = 0\text{V}$ or $V_{CC}$	$t_{RC}(2)$	—	—	ns

1.  $V_{CC} = 2\text{V}$ ,  $T_A = +25^\circ\text{C}$
2.  $t_{RC}$  = Read Cycle Time

**Timing Waveform Low  $V_{CC}$  Data Retention Waveform**

**Ordering Information**

Part Number	Access Time (Max.)	Package
UM6116-5	55 ns	Plastic
UM6116J-5	55 ns	CERDIP